# **ON Semiconductor**

### Is Now



To learn more about onsemi™, please visit our website at www.onsemi.com

onsemi and ONSEMI. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application,

# Bipolar Power Transistors 100 V, 3.0 A, Low V<sub>CE(sat)</sub> PNP Transistor

## NSV1C300CT

ON Semiconductor's  $e^2$ PowerEdge family of low  $V_{CE(sat)}$  transistors are surface mount devices featuring ultra-low saturation voltage,  $V_{CE(sat)}$ , and high current gain capability. These are designed for use in lower voltage, high speed switching applications where affordable efficient energy control is important.

Housed in an ultra slim LFPAK4 5x6 package, typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, digital cameras and MP3 players where PCB space is at a premium. The LFPAK4 5x6 package also contains wettable flanks which are a requirement for the automotive industry's optical inspection methods that are implemented in end applications such as air bag deployment, powertrain control units, and instrument clusters.

#### **Features**

- Complement to NSS1C301CT
- Ultra-slim LFPAK4 Package (5 x 6 mm) with Wettable Flanks
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### MAXIMUM RATINGS (T<sub>C</sub> = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	-100	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-140	Vdc
Emitter-Base Voltage	V <sub>EB</sub>	-6.0	Vdc
Base Current - Continuous	Ι <sub>Β</sub>	-0.5	Adc
Collector Current - Continuous	I <sub>C</sub>	-3.0	Adc
Collector Current - Peak	I <sub>CM</sub>	-6.0	Α
Total Power Dissipation Total $P_D @ T_A = 25^{\circ}C$ (Note 1) Total $P_D @ T_A = 25^{\circ}C$ (Note 2)	P <sub>D</sub>	5.0 1.0	W
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

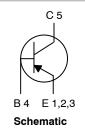
- 1. Mounted on 1" sq. (645 sq. mm) Collector pad on FR-4 bd material.
- 2. Mounted on 0.012" sq. (7.6 sq. mm) Collector pad on FR-4 bd material.



#### ON Semiconductor®

www.onsemi.com

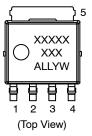
# PNP TRANSISTOR -3.0 AMPERES -100 VOLTS





LFPAK4 5x6 CASE 760AB

#### **MARKING DIAGRAM**



XXXXXX = Specific Device Code
A = Assembly Location
LL = Wafer Lot

Y = Year
W = Work Week

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSS1C300CTWG	LFPAK4 5x6 (Pb-Free)	3,000 / Tape & Reel
NSV1C300CTWG*	LFPAK 5x6 (Pb-Free)	3,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case Junction-to-Ambient on 1" sq. (645 sq. mm) Collector pad on FR-4 bd material Junction-to-Ambient on 0.012" sq. (7.6 sq. mm) Collector pad on FR-4 bd material	$egin{array}{c} R_{ hetaJA} \ R_{ hetaJA} \end{array}$	40 120	°C/W

#### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (I <sub>C</sub> = -10 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	-100	-	-	Vdc
Collector – Base Breakdown Voltage (I <sub>C</sub> = -0.1 mAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	-140	-	-	Vdc
Emitter – Base Breakdown Voltage (I <sub>E</sub> = -0.1 mAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	-6.0	-	-	Vdc
Collector Cutoff Current (V <sub>CB</sub> = -140 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>	-	-	-0.1	μAdc
Emitter Cutoff Current (V <sub>EB</sub> = -6.0 Vdc)	I <sub>EBO</sub>	-	-	-0.1	μAdc
ON CHARACTERISTICS	•				
DC Current Gain (Note 3) $ \begin{array}{l} (I_C = -0.1 \text{ A, } V_{CE} = -2.0 \text{ V}) \\ (I_C = -0.5 \text{ A, } V_{CE} = -2.0 \text{ V}) \\ (I_C = -1.0 \text{ A, } V_{CE} = -2.0 \text{ V}) \\ (I_C = -3.0 \text{ A, } V_{CE} = -2.0 \text{ V}) \end{array} $	h <sub>FE</sub>	180 180 120 50	- - - -	- - 500 -	
	V <sub>CE(sat)</sub>	- - - -	- - - -	-0.070 -0.150 -0.250 -0.400	V
Base – Emitter Saturation Voltage (Note 3) (I <sub>C</sub> = -1.0 A, I <sub>B</sub> = -0.1 A)	V <sub>BE(sat)</sub>	-	-	-1.0	V
Base – Emitter Turn–on Voltage (Note 3) (I <sub>C</sub> = -1.0 A, V <sub>CE</sub> = -2.0 V)	V <sub>BE(on)</sub>	-	-	-0.900	V
Cutoff Frequency (I <sub>C</sub> = -500 mA, V <sub>CE</sub> = -10 V, f = 100 MHz)	f <sub>T</sub>	-	100	-	MHz
Input Capacitance (V <sub>EB</sub> = -5.0 V, f = 1.0 MHz)	Cibo	-	360	-	pF
Output Capacitance (V <sub>CB</sub> = -10 V, f = 1.0 MHz)	Cobo	-	60	-	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%.

<sup>\*</sup>NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

#### **TYPICAL CHARACTERISTICS**

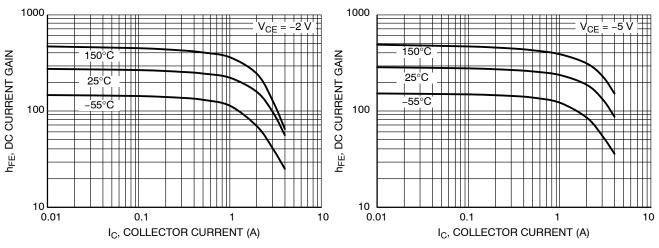


Figure 1. DC Current Gain

Figure 2. DC Current Gain

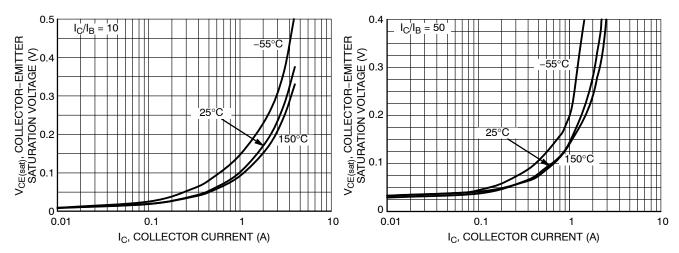


Figure 3. Collector-Emitter Saturation Voltage

Figure 4. Collector-Emitter Saturation Voltage

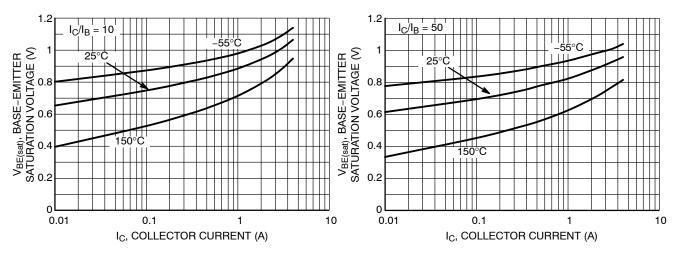


Figure 5. Base-Emitter Saturation Voltage

Figure 6. Base-Emitter Saturation Voltage

#### **TYPICAL CHARACTERISTICS**

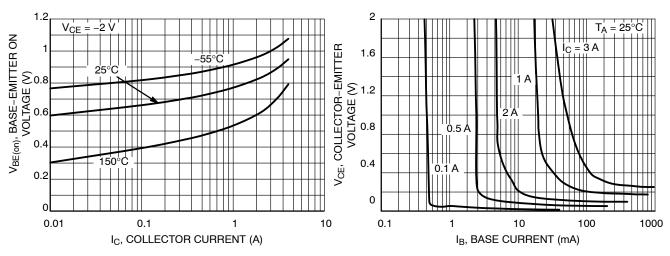


Figure 7. Base-Emitter On Voltage

Figure 8. Collector Saturation Region

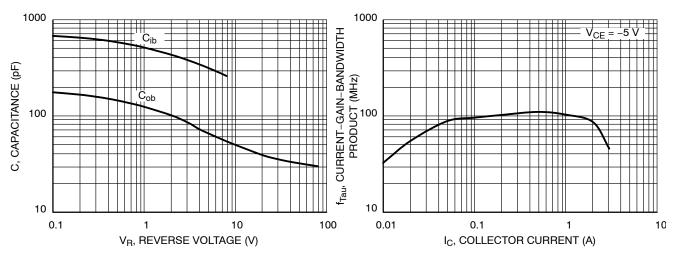


Figure 9. Capacitance

Figure 10. Current-Gain-Bandwidth Product

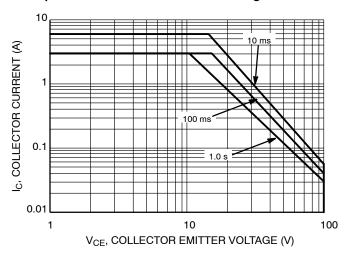


Figure 11. Safe Operating Area

#### **TYPICAL CHARACTERISTICS**

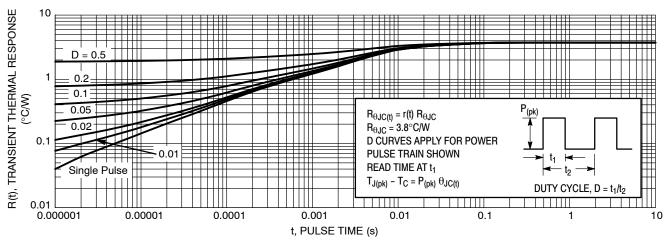
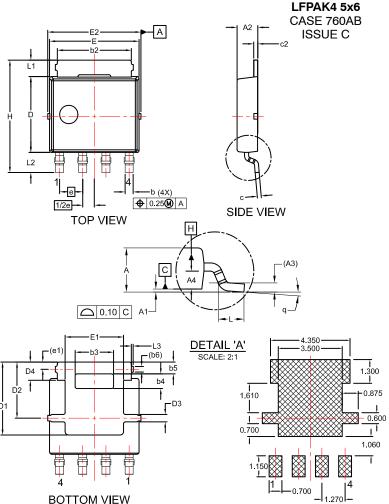


Figure 12. Typical Transient Thermal Response, Junction-to-Case

#### PACKAGE DIMENSIONS



#### RECOMMENDED LAND PATTERN

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRMD.

#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
- 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.150mm PER SIDE.
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 5. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

UNIT IN MILLIMETER				
DIM	MIN	NOM	MAX	
Α	1.10	1.20	1.30	
A1	0.00	0.08	0.15	
A2	1.10	1.15	1.20	
A3	0.25 REF			
A4	0.45	0.50	0.55	
b	0.40	0.45	0.50	
b2	3.80	4.10	4.40	
b3	2.00	2.10	2.20	
b4	0.70	0.80	0.90	
b5	0.55	0.65	0.75	
b6	0.31 REF			
С	0.19	0.22	0.25	
c2	0.19	0.22	0.25	
D	4.05	4.15	4.25	
D1	3,80	4.00	4.20	
D2	3.00	3.10	3.20	
D3	0.30	0.40	0.50	
D4	0.90	1.00	1.10	
Е	4.80	4.90	5.00	
E1	3.10	3.20	3.30	
E2	5.00	5.15	5.30	
е	1.27 BSC			
1/2e	0,635 BSC			
e1	0.40 REF			
Н	6.00	6.15	6.30	
L	0.40	0.65	0.85	
L1	0.80	0.90	1.00	
L2	0.90	1.10	1.30	
L3	0.00	0.10	0.20	
q	0°	4°	8°	

ON Semiconductor and the are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and see no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and

#### **PUBLICATION ORDERING INFORMATION**

LITERATURE FULFILLMENT:
Email Requests to: orderlit@onsemi.com

ON Semiconductor Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative